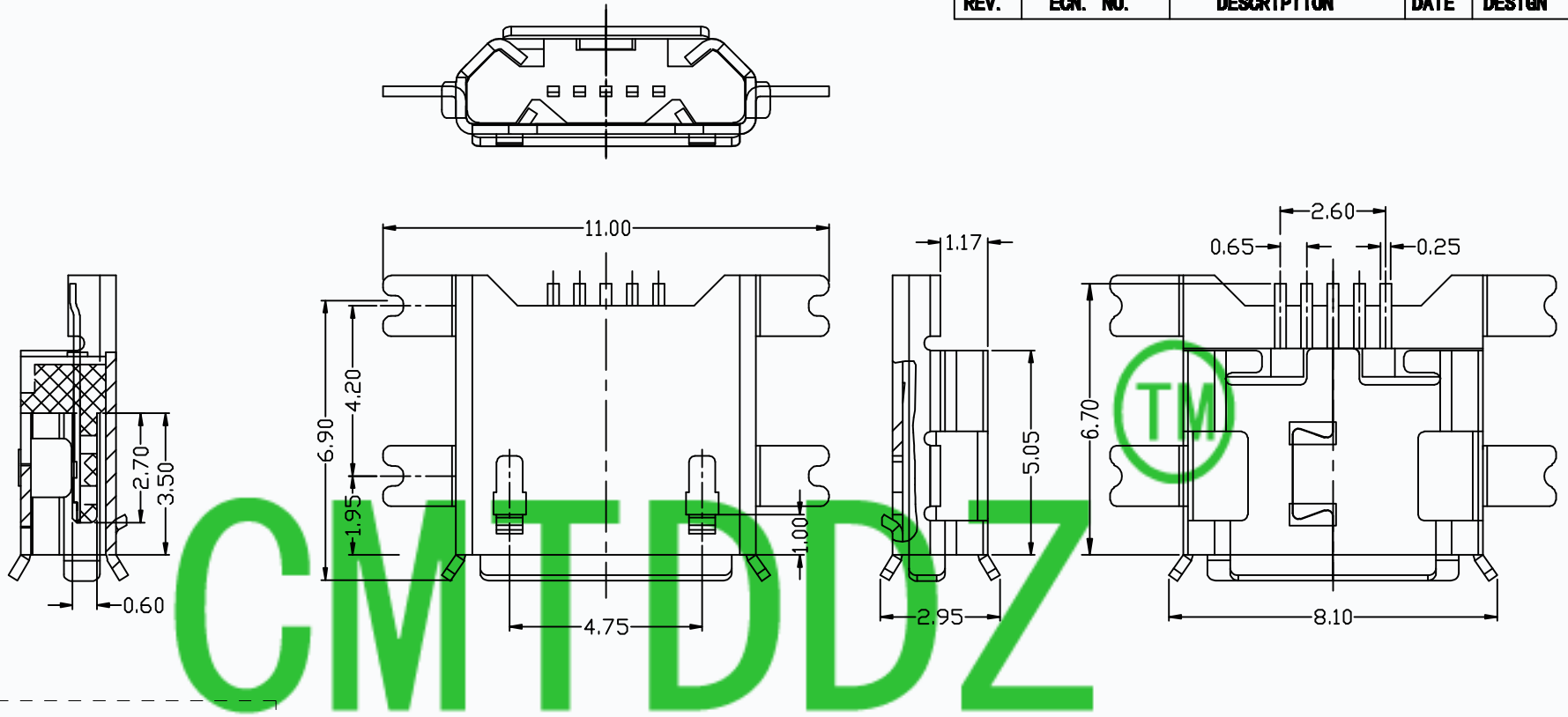
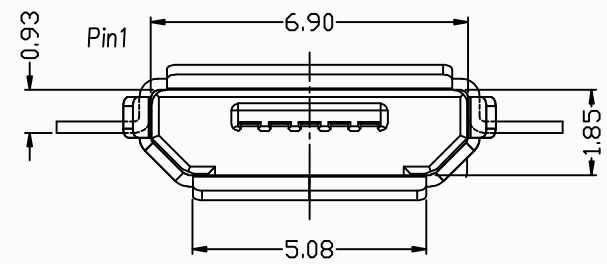
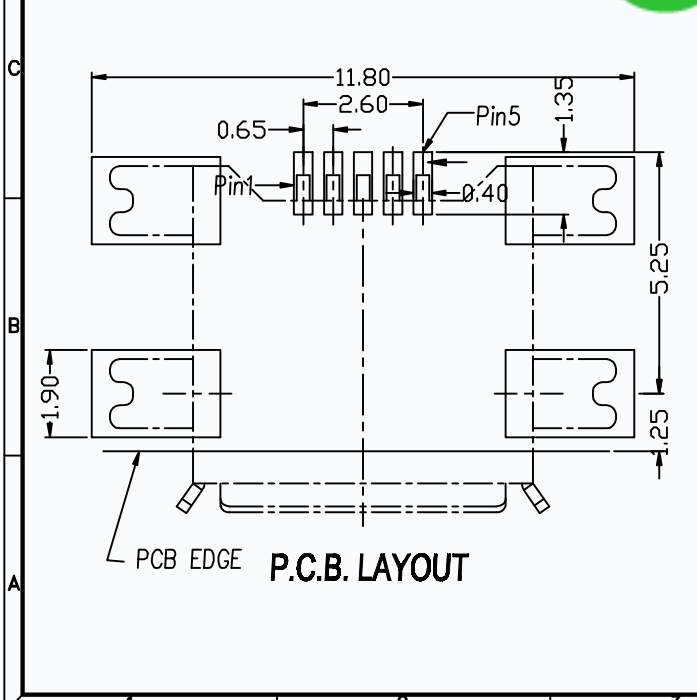


REV.	ECN. NO.	DESCRIPTION	DATE	DESIGN
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CMTDDZ



**Notes:**

- 1. Materials:**
  - 1.1 Housing: High temperature thermoplastic with g.f,UL94 v-0.
  - 1.2 Contact: copper alloy,t=0.20mm.
  - 1.3 Shell: copper alloy,t=0.25mm.
- 2. Specifications:**
  - 2.1. Current rating: 1 A Max.
  - 2.2. Dielectric withstanding-voltage: 100 V(ac) for 1 min.
  - 2.3. Contact resistance: 50 mW Max.
  - 2.4. Insulation resistance: 100 MW Min.
  - 2.5. Total mating force: 3.57 Kgf Max.
  - 2.6. Total unmating force: 1.0 Kgf Min.0.81~2.05 Kgf Min.after 10000 insertion/extraction cycles
  - 2.7. Temperature range: -30°C~+80°C

UNITS mm	NAME (INTENDED USE)		<b>东莞市田都电子有限公司</b> <small>DONGGUAN TIANDU ELECTRONICS CO.,LTD</small>		
	MAT'L	MODEL NO. T10-050B13	TITLE: micro usb b type四脚沉板1.17mm(SMT) 卷边		
FINISH	APPD:	DRG NO. : <b>CMTD10-00903-04A</b>			
	CHKD:	角法 FIG.			
Q'TY	DR: MC	11/9'09	SCALE 1/1	SHEET 1/1	REV. A1